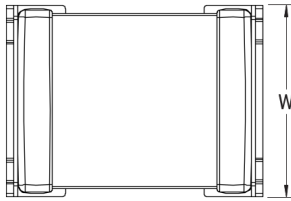
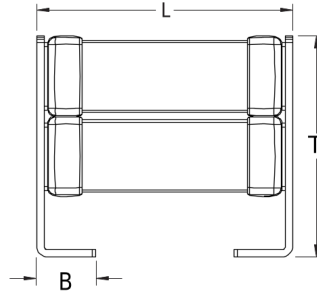


TOP VIEW  
Single or Double Chip Stack



SIDE VIEW  
Double Chip Stack



Click [here](#) for the 3D model.

### Dimensions

L	3.5mm +/-0.3mm
W	2.6mm +/-0.3mm
T	6.15mm +/-0.15mm
B	0.8mm +/-0.15mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

### General Information

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Double Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	290 mg
Chip Size	1210-2
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

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